

Press Release

Viscom's S3088 SPI inspection system wins Global Technology Award

Duluth, GA, November 2017 — **Viscom announces that it was awarded a 2017 Global Technology Award in the category of Inspection – SPI. The award was presented to the company during a ceremony on Tuesday, Nov. 14, 2017 that took place during productronica in Munich, Germany.**

The award-winning inspection system S3088 SPI combines the advantages of market-leading Viscom AOI systems with powerful 3D SPI sensor technology and inspects the solder paste deposits with the highest possible speed and precision. Even the most demanding assemblies with CSPs or micro BGAs and pad sizes of 01005 are reliably inspected.



In SMT electronic assembly production, 3D solder paste print inspection has established itself as the additional inspection gate to complement optical or X-ray inspection of electronic assemblies. The key task of the 3D SPI is detecting impermissible printed pads in terms of volume, form, smearing, paste bridges and offset.

The Viscom SPI offers far more than just defect detection: By evaluating the 3D measurement data and linking the results with the paste printer, placement systems, AOI and X-ray inspection, you have the possibility for effective process control. Furthermore, through the Viscom Quality Uplink, the measurement data can also be used in various ways during subsequent production steps.

Viscom offers a complete lineup of 3D inspection systems for the electronics industry. The portfolio includes solder paste inspection (SPI), automatic optical inspection (AOI), and X-ray systems (AXI/MXI) with micro-computed tomography (μ CT) for the highest defect coverage.

Premiering in 2005, the Global Technology Awards program is an annual celebration of product excellence in electronics surface mount assembly. Premier products based on the finest examples of creative advancement in technology are chosen by a distinguished panel of industry experts.

For more information about Viscom, visit www.viscom.com.

About Viscom

Viscom AG manufactures and sells high-quality automatic optical and X-ray inspection systems. The company is one of the leading suppliers of 3D solder paste inspection, component placement and solder joint inspection equipment in the PCB assembly market. Viscom systems ensure quality in surface mount technology production lines, where they can be interlinked to further improve productivity. The company's headquarters and manufacturing operation is located in Hanover, Germany. With a wide network of branches, applications and service centers, Viscom is represented throughout Europe, Asia and the Americas. Founded in 1984, Viscom has been listed on the Frankfurt Stock Exchange (ISIN: DE0007846867) since 2006. For more information, visit www.viscom.com.